

MOS FIELD EFFECT TRANSISTOR

2SJ449

SWITCHING P-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SJ449 is P-Channel MOS Field Effect Transistor designed for high voltage switching applications.

FEATURES

- Low On-Resistance
 $R_{DS(on)} = 0.8 \Omega \text{ MAX. (@ } V_{GS} = -10 \text{ V, } I_D = -3.0 \text{ A)}$
- Low C_{iss} $C_{iss} = 1040 \text{ pF TYP.}$
- High Avalanche Capability Ratings
- Isolated TO-220 Package

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

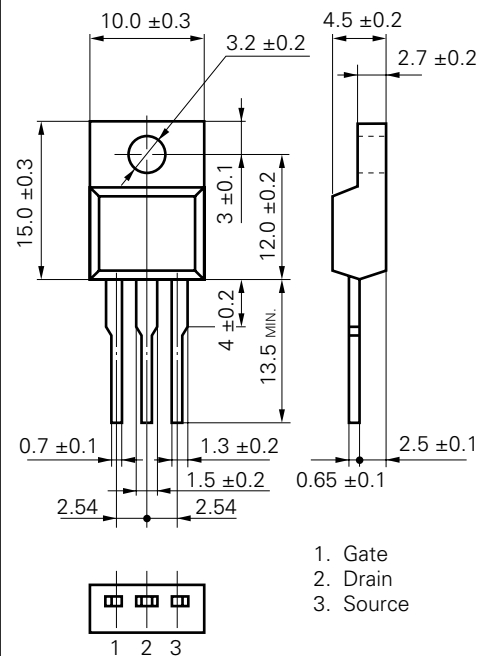
Drain to Source Voltage	V_{DSS}	-250	V
Gate to Source Voltage	V_{GSS}	∓ 30	V
Drain Current (DC)	$I_{D(DC)}$	∓ 6.0	A
Drain Current (pulse)*	$I_{D(pulse)}$	∓ 24	A
Total Power Dissipation ($T_c = 25^\circ\text{C}$)	P_{T1}	35	W
Total Power Dissipation ($T_A = 25^\circ\text{C}$)	P_{T2}	2.0	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$
Single Avalanche Current**	I_{AS}	-6.0	A
Single Avalanche Energy**	E_{AS}	180	mJ

* $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

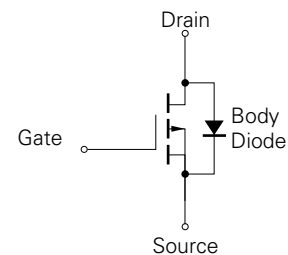
** Starting $T_{ch} = 25^\circ\text{C}$, $R_G = 25 \Omega$, $V_{GS} = -20 \text{ V} \rightarrow 0$

PACKAGE DIMENSIONS

(in millimeters)



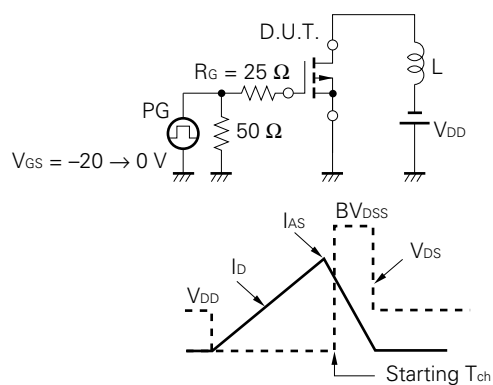
MP-45F (ISOLATED TO-220)



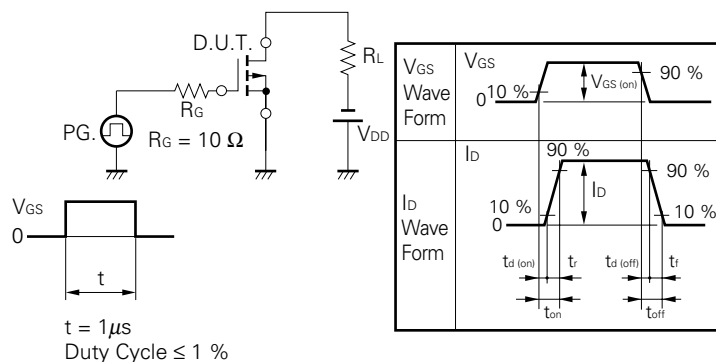
ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	$R_{DS(on)}$		0.55	0.8	Ω	$V_{GS} = -10\text{ V}$, $I_D = -3.0\text{ A}$
Gate to Source Cutoff Voltage	$V_{GS(off)}$	-4.0	-4.8	-5.5	V	$V_{DS} = -10\text{ V}$, $I_D = -1\text{ mA}$
Forward Transfer Admittance	$ y_{fs} $	2.0	3.5		S	$V_{DS} = -10\text{ V}$, $I_D = -3.0\text{ A}$
Drain Leakage Current	I_{DSS}			-100	μA	$V_{DS} = -250\text{ V}$, $V_{GS} = 0$
Gate to Source Leakage Current	I_{GSS}			∓ 100	nA	$V_{GS} = \mp 30\text{ V}$, $V_{DS} = 0$
Input Capacitance	C_{iss}		1040		pF	$V_{DS} = -10\text{ V}$ $V_{GS} = 0$ $f = 1\text{ MHz}$
Output Capacitance	C_{oss}		360		pF	
Reverse Transfer Capacitance	C_{rss}		70		pF	
Turn-On Delay Time	$t_{d(on)}$		24		ns	
Rise Time	t_r		16		ns	$I_D = -3.0\text{ A}$ $V_{GS(on)} = -10\text{ V}$ $V_{DD} = -125\text{ V}$ $R_G = 10\text{ }\Omega$, $R_L = 42\text{ }\Omega$
Turn-Off Delay Time	$t_{d(off)}$		47		ns	
Fall Time	t_f		14		ns	
Total Gate Charge	Q_G		23.1		nC	$I_D = -6.0\text{ A}$ $V_{DD} = -200\text{ V}$ $V_{GS} = -10\text{ V}$
Gate to Source Charge	Q_{GS}		7.1		nC	
Gate to Drain Charge	Q_{GD}		12.9		nC	
Body Diode Forward Voltage	$V_{F(S-D)}$		0.92		V	$I_F = -6.0\text{ A}$, $V_{GS} = 0$
Reverse Recovery Time	t_{rr}		155		ns	$I_F = -6.0\text{ A}$, $V_{GS} = 0$ $di/dt = 50\text{ A}/\mu\text{s}$
Reverse Recovery Charge	Q_{rr}		930		nC	

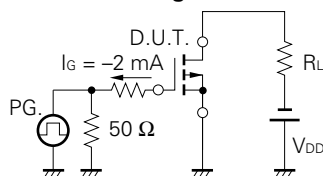
Test Circuit 1 Avalanche Capability



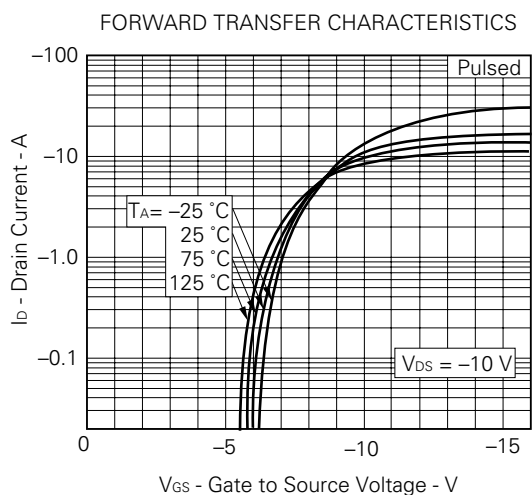
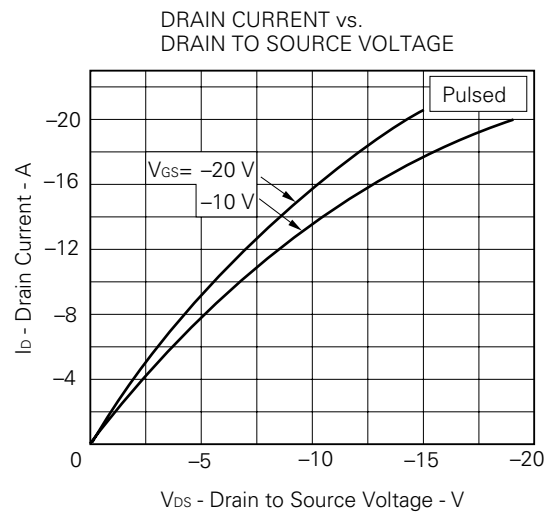
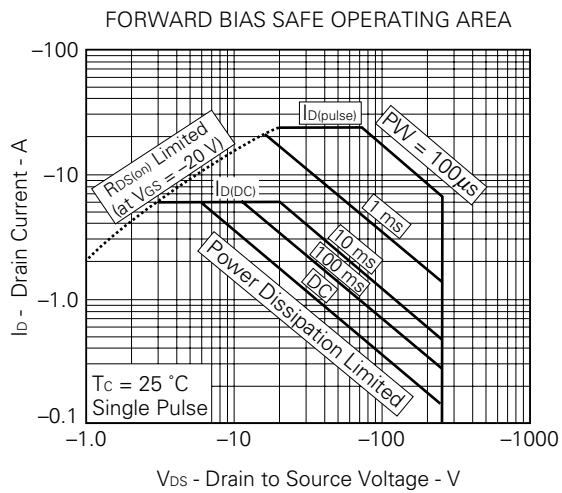
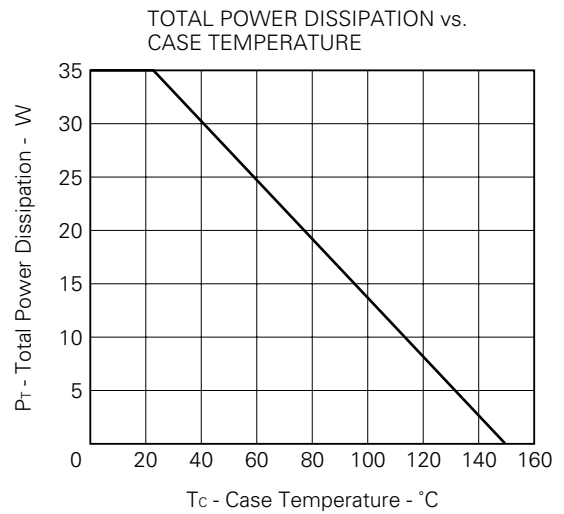
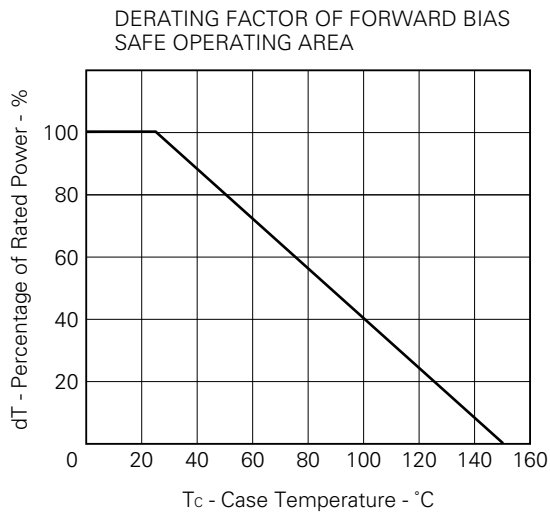
Test Circuit 2 Switching Time



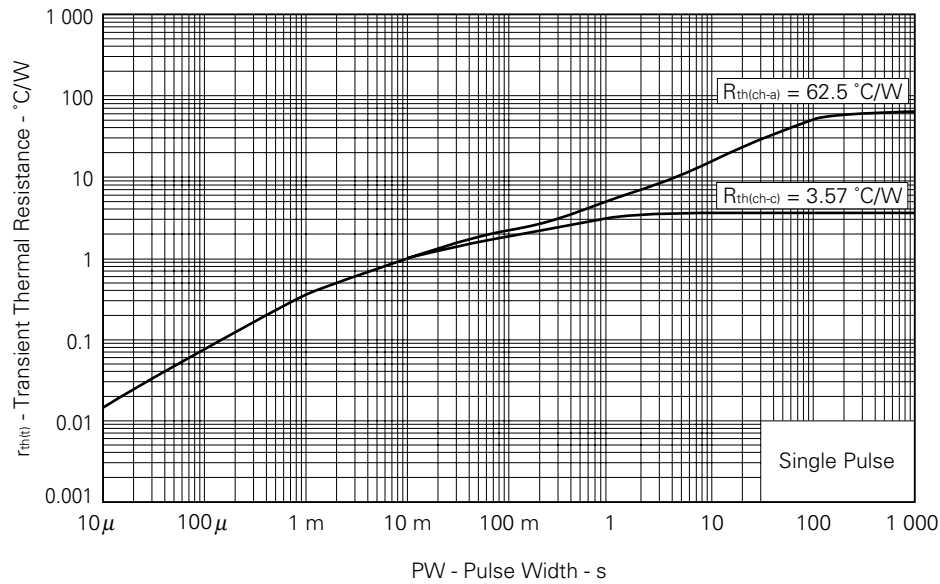
Test Circuit 3 Gate Charge



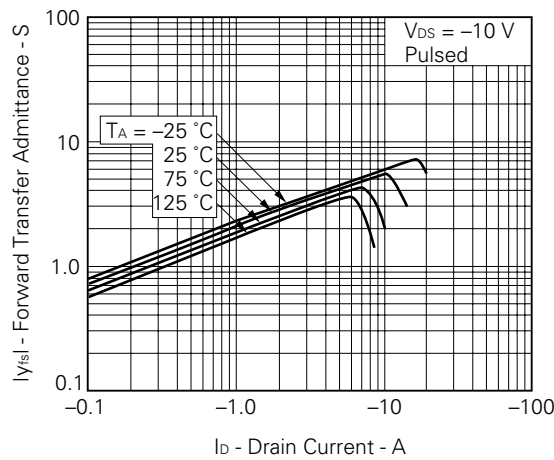
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

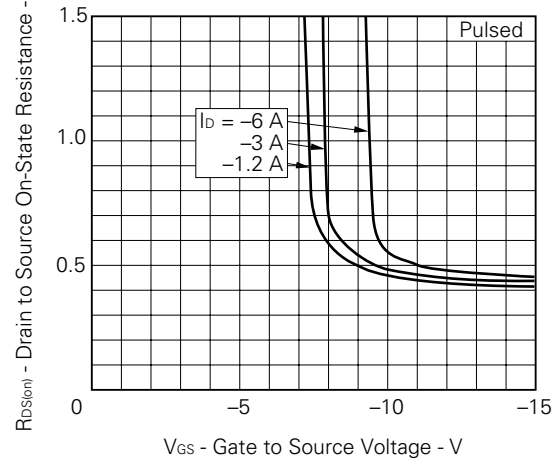
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



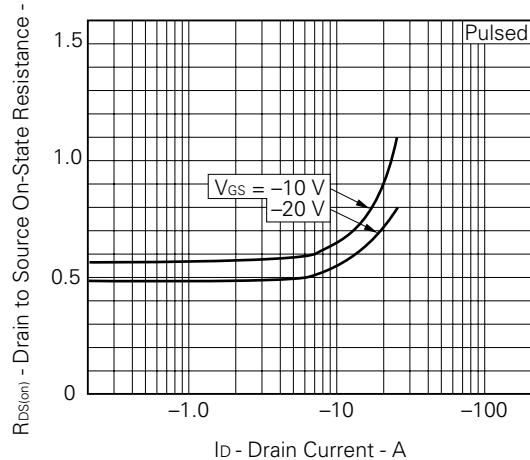
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



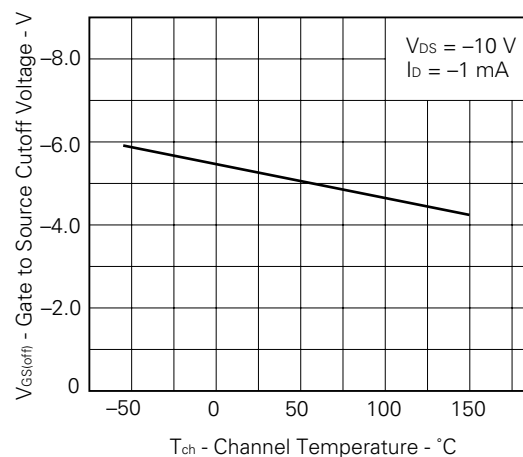
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



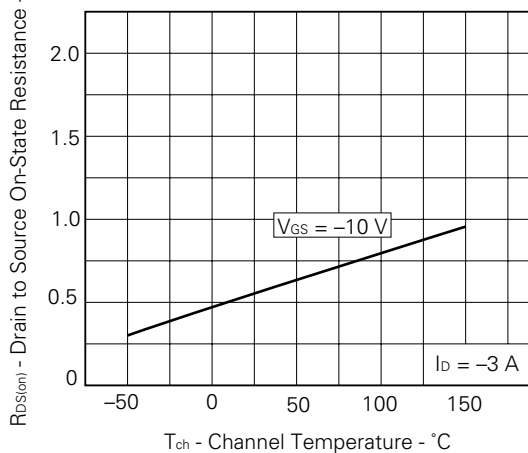
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



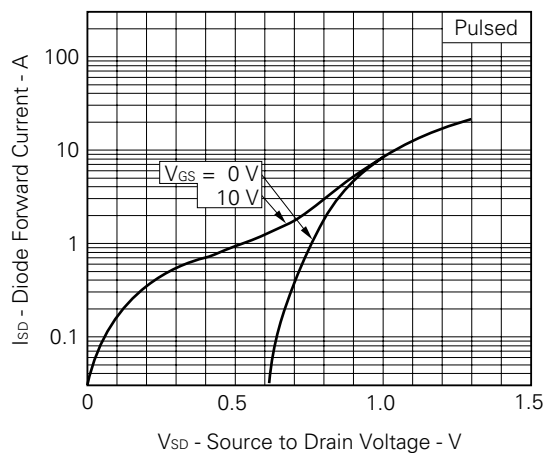
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



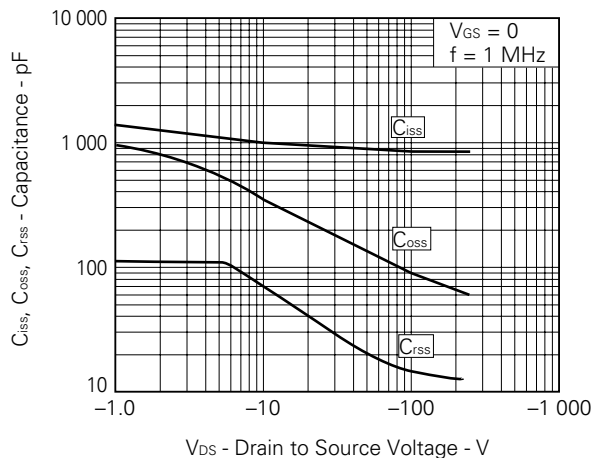
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



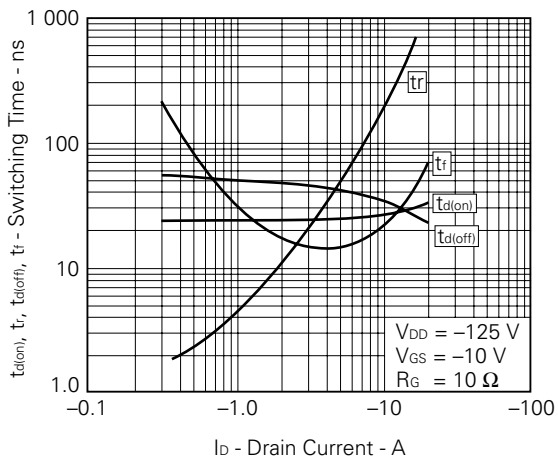
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



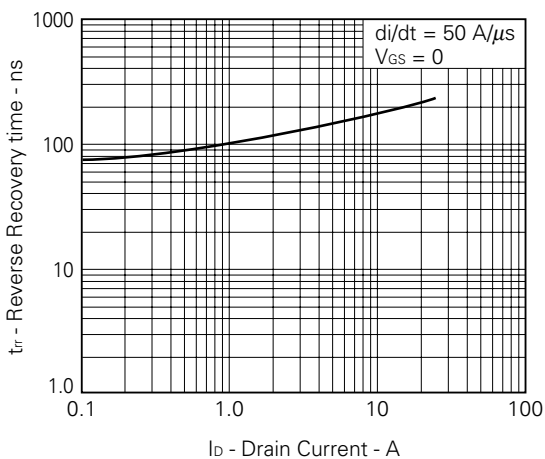
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



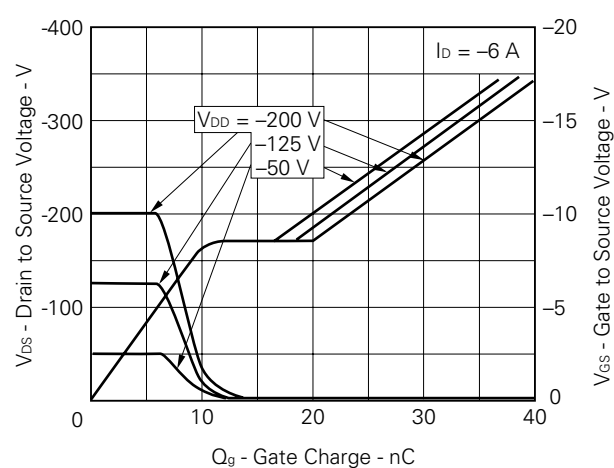
SWITCHING CHARACTERISTICS

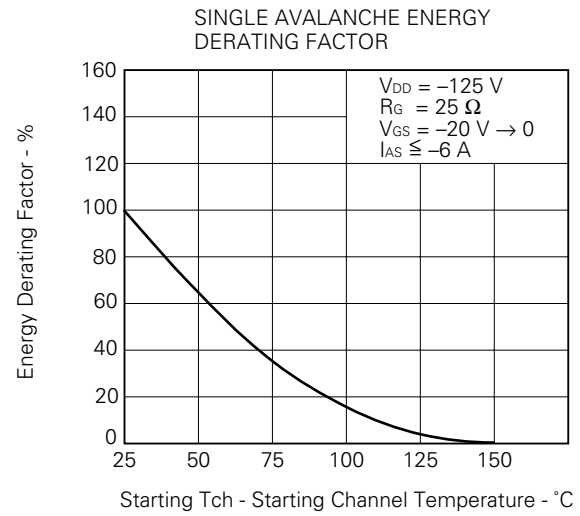
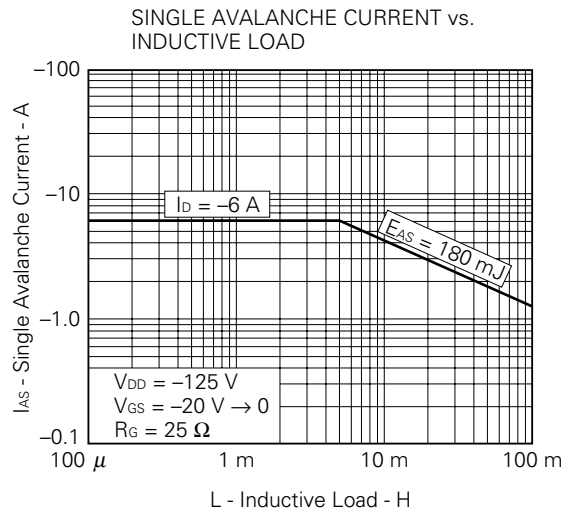


REVERSE RECOVERY TIME vs. DRAIN CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS





REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

[MEMO]

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Anti-radioactive design is not implemented in this product.